

 <b>D. G. M. E.</b>	DG25N120	版本号：V1.0
	绝缘栅双极型晶体管	

## 产品概述

IGBT既有功率MOSFET输入阻抗高，控制功率小，易于驱动，控制简单的特点，又有双极晶体管的导通电压低，通态电流大，损耗小的显著优点。在提倡节能减排、低碳经济的时代，具备节能效率高，便于规模化生产等优点的IGBT已成为功率半导体市场发展的主流技术。

## 产品特点

- 采用NPT技术
- 高开关速度： $t_f = 170\text{ns}$
- 低饱和压降： $V_{CE(sat)} = 2.2\text{V} @ I_c=25\text{A}$
- 高输入阻抗
- 热稳定性好

## 应用领域

主要用于感应加热领域，如电磁炉。

## 特征参数

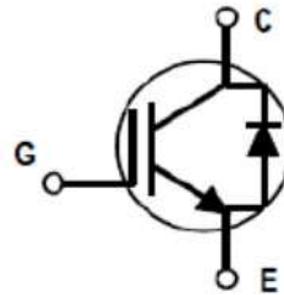
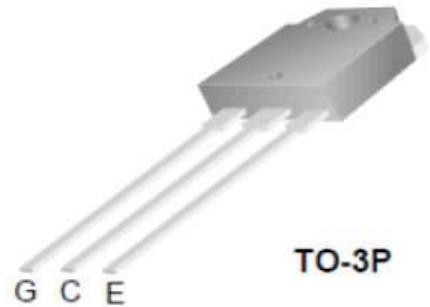
符号	额定值	单位
$V_{(BR)CES}$	1200	V
$I_c$	25	A
$V_{CE(sat)}$	2.2	V

## 极限值

除非另有规定， $T_a=25^\circ\text{C}$

参数名称	符号	额定值	单位
集电极-发射极击穿电压	$V_{CE}$	1200	V
连续集电极	$I_c$	25	A
脉冲集电极电流	$I_{cpuls}$	60	A
栅-发射极电压	$V_{GE}$	$\pm 30$	V
耗散功率 $T_c=25^\circ\text{C}$	$P_D$	170	W
工作温度范围	$T_J$	-55 to +150	$^\circ\text{C}$
贮存温度范围	$T_{STG}$	-55 to +150	$^\circ\text{C}$

封装：TO-3P

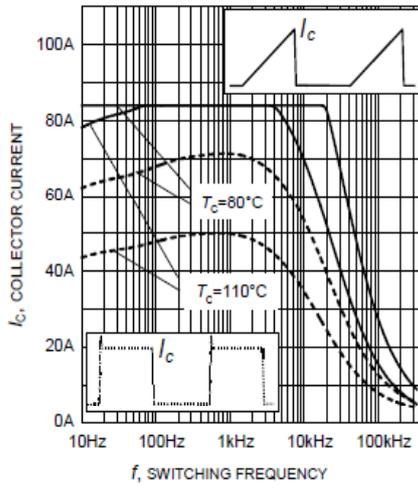


## 电参数

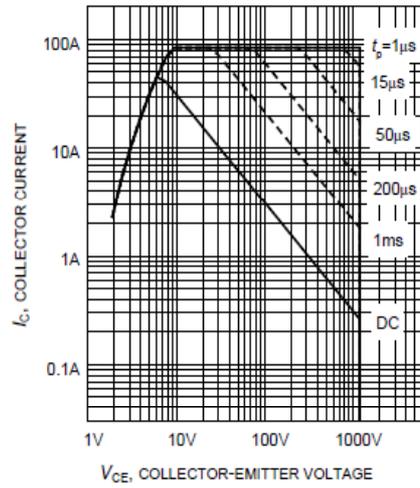
除非另有规定,  $T_a=25^{\circ}\text{C}$

参数名称	符号	测试条件	规范值			单位
			最小	典型	最大	
$V_{(BR)CES}$	集电极-发射极击穿电压	$V_{GE}=0$ $I_C=1000\mu\text{A}$	1200			V
$I_{CES}$	集电极-发射极泄漏电流	$V_{GE}=0$ $V_{CE}=1200\text{V}$			180	$\mu\text{A}$
$I_{GSS}$	栅极-发射极泄漏电流	$V_{CE}=0$ $V_{GE}=20\text{V}$			100	nA
$V_{GE(th)}$	开启电压	$V_{GE}=V_{CE}$ , $I_D=600\mu\text{A}$	3.0		6.0	V
$V_{CE(sat)}$	集电极-发射极饱和压降	$V_{GE}=15\text{V}$ , $I_C=25\text{A}$		2.2	2.8	V
$C_{iss}$	输入电容	$V_{CE}=25\text{V}$ , $V_{GE}=0$ , $f=1\text{MHz}$		1450	1750	pF
$C_{oss}$	输出电容			110	130	pF
$C_{rss}$	反向恢复电容			70	85	pF
$Q_g$	栅电荷	$V_{CC}=960\text{V}$ $I_C=25\text{A}$ $V_{GE}=15\text{V}$		199	270	nC
$t_d(on)$	导通延时	$V_{CC}=800\text{V}$ , $I_C=25\text{A}$ , $R_G=33\ \Omega$ 感性负载		38	50	ns
$t_r$	上升时间			26	40	ns
$t_d(off)$	关断延时			240	350	ns
$t_f$	下降时间			180	230	ns
$E_{on}$	开启能量			2.1	2.6	mJ
$E_{off}$	关断能量			0.95	1.2	mJ
$t_d(on)$	导通延时	$V_{CC}=800\text{V}$ , $I_C=25\text{A}$ , $R_G=33\ \Omega$ $T_C=150^{\circ}\text{C}$ 感性负载		40	55	ns
$t_r$	上升时间			28	45	ns
$t_d(off)$	关断延时			242	365	ns
$t_f$	下降时间			188	250	ns
$E_{on}$	开启能量			2.2	2.7	mJ
$E_{off}$	关断能量			0.99	1.3	mJ
$V_{FM}$	二极管正向压降	$I_F=25\text{A}$		1.9	2.5	V
$t_{rr}$	二极管反向恢复时间	$I_F=25\text{A}$ $di/dt=200\text{A}/\mu\text{s}$		240	330	ns
$I_{rr}$	二极管反向峰值电流			31	40	A
$Q_{rr}$	二极管反向恢复电荷			2980	6750	nC

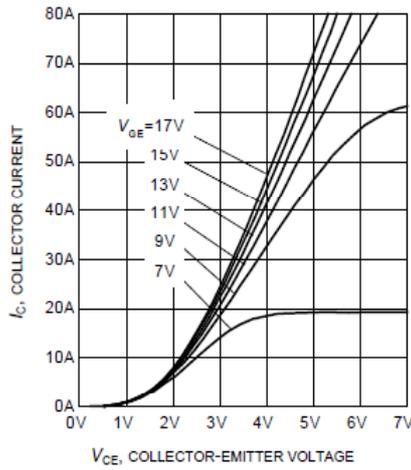
## 典型特性曲线



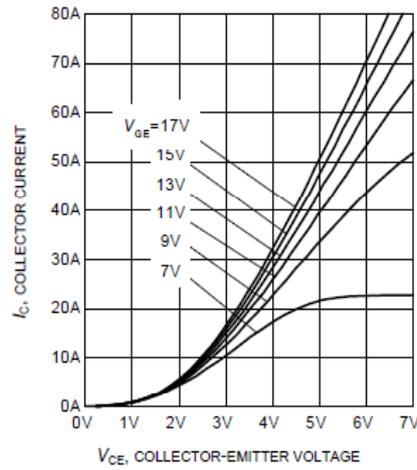
集电极电流与开关频率的关系曲线



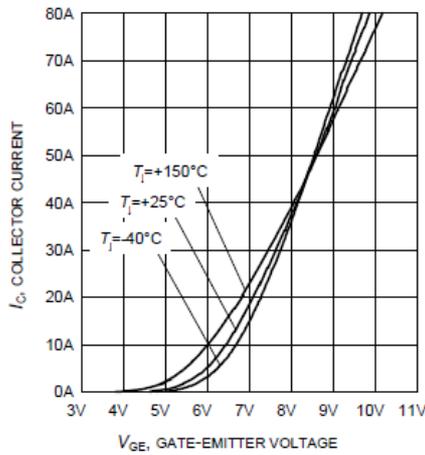
安全工作区



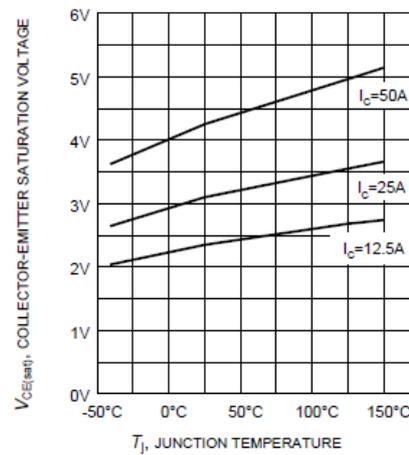
输出特性曲线 ( $T_C = 25^\circ\text{C}$ )



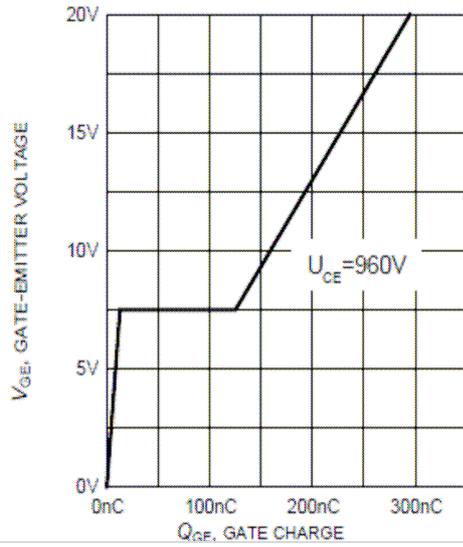
输出特性曲线 ( $T_C = 150^\circ\text{C}$ )



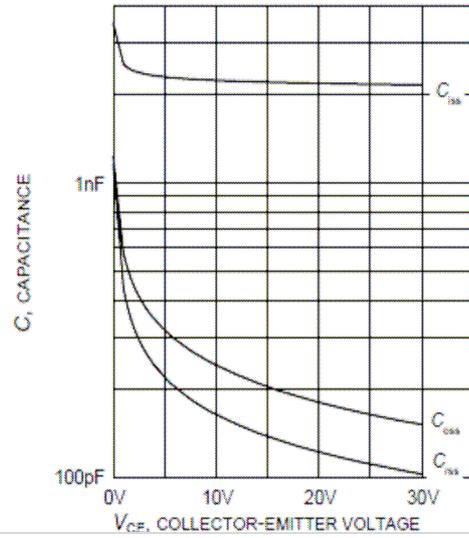
传输特性曲线



集电极-发射极饱和压降与结温的关系曲线



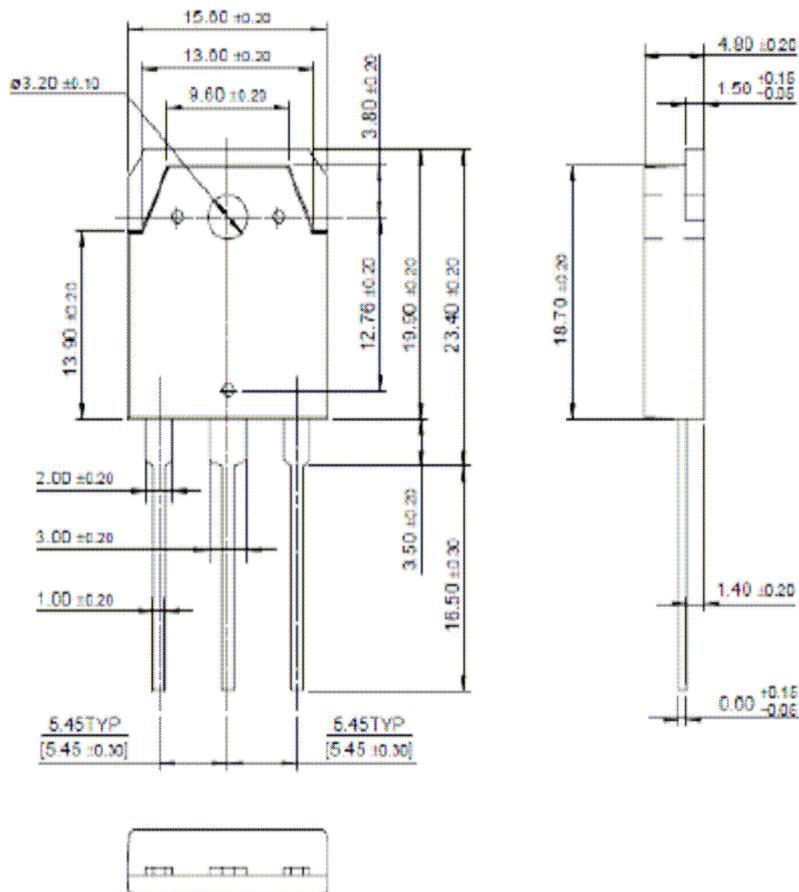
栅电荷特性曲线  
( $I_C=15A$ )



电容与集电极-发射极电压关系曲线  
( $V_{GE}=0V$   $f=1MHz$ )

附录：封装尺寸

TO-3P



 <b>D. G. M. E.</b>	DG25N120	Version No. : V1.0
	IGBT	

## General Description

IGBT has been the major switching device in power electronic applications as it has the merits of both power bipolar and power MOSFET. It has been widely used in high voltage field, which ranges from industrial areas such as inverters, high voltage switch, and motor operation to PDP or home appliance.

## Features

- Employing NPT technology
- High speed switching:  $t_f = 170\text{ns}$
- Low saturation voltage:  $V_{CE(sat)} = 2.2\text{V} @ I_c=25\text{A}$
- High input impedance

## Applications

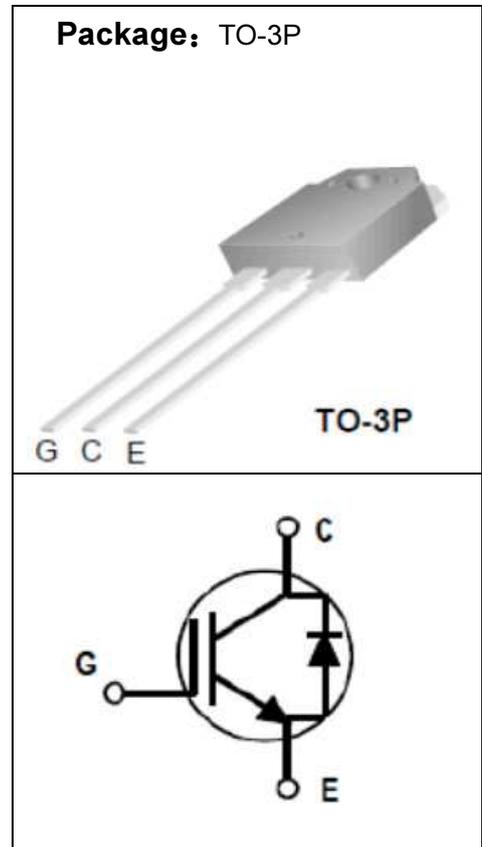
Induction Heating

## Characteristic parameter

SYMBOL	Value	Unit
$V_{(BR)CES}$	1200	V
$I_c$	25	A
$V_{CE(sat)}$	2.2	V

## Maximum Ratings

$T_c=25^\circ\text{C}$ , unless otherwise specified



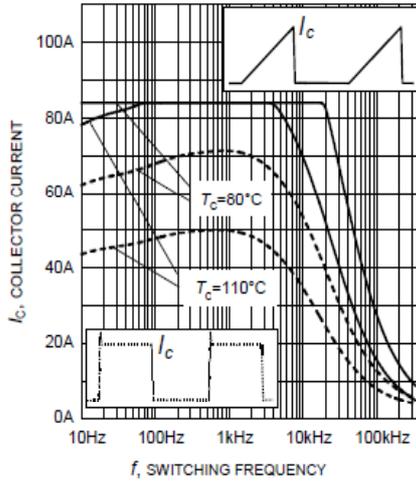
PARAMETER	SYMBOL	Value	Unit
Collector-emitter voltage	$V_{CE}$	1200	V
DC collector	$I_c$	25	A
Pulsed collector current	$I_{Cpuls}$	60	A
Gate-emitter voltage	$V_{GE}$	$\pm 30$	V
Power dissipation $T_c=25^\circ\text{C}$	$P_D$	170	W
Operating junction temperature	$T_J$	-55 to +150	$^\circ\text{C}$
Storage temperature	$T_{STG}$	-55 to +150	$^\circ\text{C}$

## Electrical Characteristic

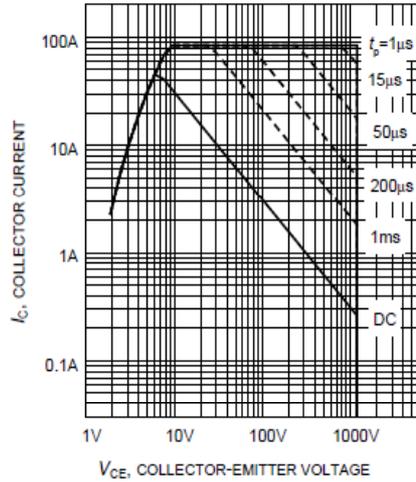
at  $T_c=25^\circ\text{C}$ , unless otherwise specified

PARAMETER	SYMBOL	Conditions	Value			Unit
			Min.	Typ.	Max.	
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE}=0$ $I_C=1000\mu\text{A}$	1200			V
$I_{CES}$	Zero gate voltage collector current	$V_{GE}=0$ $V_{CE}=1200\text{V}$			180	$\mu\text{A}$
$I_{GSS}$	Gate-emitter leakage current	$V_{CE}=0$ $V_{GE}=20\text{V}$			100	nA
$V_{GE(th)}$	Gate-emitter threshold voltage	$V_{GE}=V_{CE}$ , $I_D=600\mu\text{A}$	3.0		6.0	V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE}=15\text{V}$ , $I_C=25\text{A}$		2.2	2.8	V
$C_{iss}$	Input capacitance	$V_{CE}=25\text{V}$ , $V_{GE}=0$ , $f=1\text{MHz}$		1450	1750	pF
$C_{oss}$	output capacitance			110	130	pF
$C_{rss}$	Reverse transfer capacitance			70	85	pF
$Q_g$	Gate charge	$V_{CC}=960\text{V}$ $I_C=25\text{A}$ $V_{GE}=15\text{V}$		199	270	nC
$t_d(on)$	Turn-on delay time	$V_{CC}=800\text{V}$ , $I_C=25\text{A}$ , $R_G=33\ \Omega$ Inductive load		38	50	ns
$t_r$	Rise time			26	40	ns
$t_d(off)$	Turn-off delay time			240	350	ns
$t_f$	Fall time			180	230	ns
$E_{on}$	Turn-on energy			2.1	2.6	mJ
$E_{off}$	Turn-off energy			0.95	1.2	mJ
$t_d(on)$	Turn-on delay time	$V_{CC}=800\text{V}$ , $I_C=25\text{A}$ , $R_G=33\ \Omega$ $T_C=150^\circ\text{C}$ Inductive load		40	55	ns
$t_r$	Rise time			28	45	ns
$t_d(off)$	Turn-off delay time			242	365	ns
$t_f$	Fall time			188	250	ns
$E_{on}$	Turn-on energy			2.2	2.7	mJ
$E_{off}$	Turn-off energy			0.99	1.3	mJ
$V_{FM}$	Diode forward voltage	$I_F=25\text{A}$		1.9	2.5	V
$t_{rr}$	Diode reverse recovery time	$I_F=25\text{A}$ $di/dt=200\text{A}/\mu\text{s}$		240	330	ns
$I_{rr}$	Diode peak reverse recovery current			31	40	A
$Q_{rr}$	Diode reverse recovery charge			2980	6750	nC

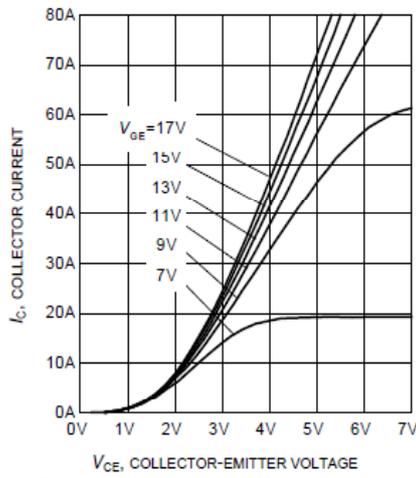
## Characteristic curves



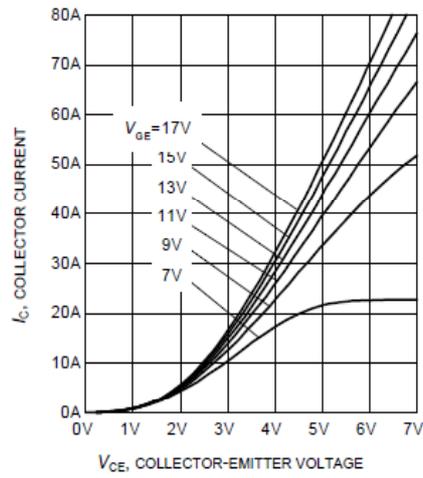
Collector current as a function of switching frequency



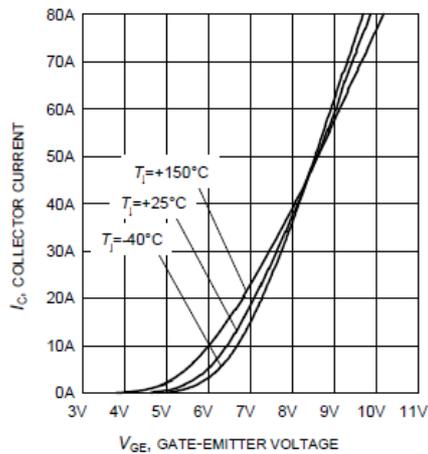
Safe operating area



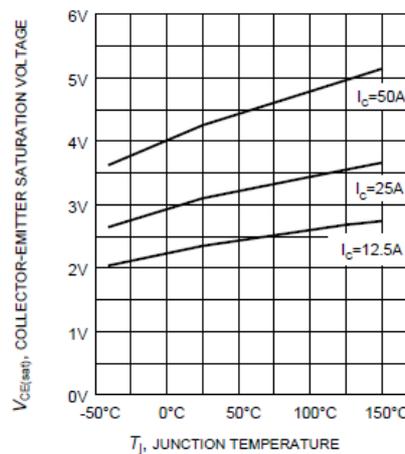
Typical output characteristic  
( $T_C = 25^\circ\text{C}$ )



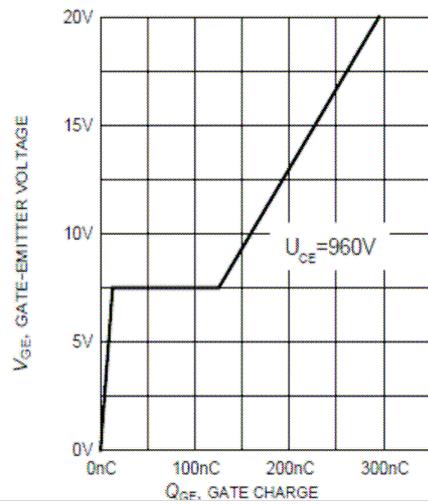
Typical output characteristic  
( $T_C = 150^\circ\text{C}$ )



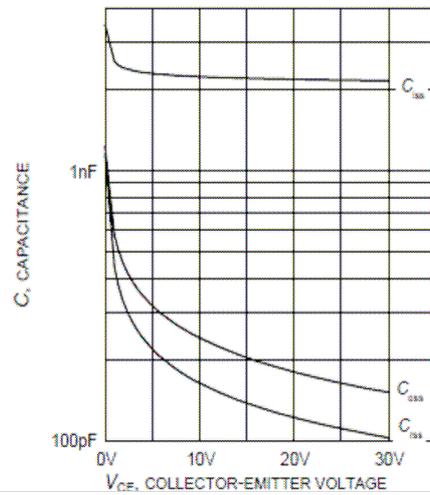
Typical transfer characteristic



Typical collector-emitter saturation voltage as a function of junction temperature



Typical gate charge  
 ( $I_C = 15A$ )



Typical capacitance as a function of  
 collector-emitter voltage  
 ( $V_{GE} = 0V$   $f = 1MHz$ )

## Package Dimension

### TO-3P

